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November 2015

FGH75T65SHDT 650 V, 75 A Field Stop Trench IGBT

Features

- Maximum Junction Temperature: T_J = 175°C
- · Positive Temperature Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage: V_{CE(sat)} = 1.6 V(Typ.) @ I_C = 75 A
- 100% of the Parts Tested for I_{LM}(1)
- · High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- RoHS Compliant

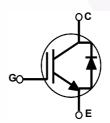
General Description

Using novel field stop IGBT technology, Fairchild's new series of field stop 3rd generation IGBTs offer the optimum performance for solar inverter, UPS, welder, telecom, ESS and PFC applications where low conduction and switching losses are essential.

Applications

· Solar Inverter, UPS, Welder, Telecom, ESS, PFC





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		FGH75T65SHDT_F155	Unit
V _{CES}	Collector to Emitter Voltage		650	V
V	Gate to Emitter Voltage		± 20	V
V_{GES}	Transient Gate to Emitter Voltage		± 30	V
I _C	Collector Current	@ T _C = 25°C	150	Α
iC	Collector Current	@ T _C = 100°C	75	Α
I _{LM (1)}	Pulsed Collector Current @ T _C = 25°C		225	Α
I _{CM (2)}	Pulsed Collector Current		225	Α
I _F	Diode Forward Current	@ T _C = 25°C	125	Α
'F	Diode Forward Current	@ T _C = 100°C	75	Α
I _{FM (2)}	Pulsed Diode Maximum Forward Current		225	Α
P _D	Maximum Power Dissipation	@ T _C = 25°C	455	W
' D	Maximum Power Dissipation	@ T _C = 100°C	227	W
T _J	Operating Junction Temperature		-55 to +175	°C
T _{stg}	Storage Temperature Range		-55 to +175	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	°C	

- Notes: 1. V_{CC} = 400 V, V_{GE} = 15 V, I_{C} = 225 A, R_{G} = 20 $\Omega,$ Inductive Load
- 2. Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	FGH75T65SHDT_F155	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case, Max.	0.33	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case, Max.	0.65	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH75T65SHDT_F155	FGH75T65SHDT	TO-247 G03	Tube	-	-	30

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	V_{GE} = 0V, I_C = 1 mA	650	-	-	V
ΔBV _{CES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	I _C = 1 mA, Reference to 25°C	-	0.6	-	V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}$, $V_{GE} = 0$ V	-	-	250	μΑ
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0 V	-	_	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I_C = 75 mA, V_{CE} = V_{GE}	4.0	5.5	7.5	V
, ,		I _C = 75 A, V _{GE} = 15 V	-	1.6	2.1	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 75 A, V _{GE} = 15 V, T _C = 175°C	-	2.28	-	٧
Dynamic C	haracteristics		•			
C _{ies}	Input Capacitance		-	3680	-	pF
C _{oes}	Output Capacitance	V _{CE} = 30 V _, V _{GE} = 0 V, f = 1MHz	-	179	-	pF
C _{res}	Reverse Transfer Capacitance	1 - IIVINZ	-	43	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		-	28	-	ns
t _r	Rise Time		-	61	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 75 A,	-	86	-/	ns
t _f	Fall Time	$R_G = 3 \Omega$, $V_{GE} = 15 V$,	-	16	- ·	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C	-	3	- /	mJ
E _{off}	Turn-Off Switching Loss		-	0.75	- //	mJ
E _{ts}	Total Switching Loss		-	3.75	- \	mJ
t _{d(on)}	Turn-On Delay Time		-	27	-	ns
t _r	Rise Time		-	62	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 75 A,	-	93	-	ns
t _f	Fall Time	$R_G = 3 \Omega$, $V_{GE} = 15 V$,	-	16	-	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 175°C	-	4.7	-	mJ
E _{off}	Turn-Off Switching Loss		-	1.03	-	mJ
E _{ts}	Total Switching Loss]	_	5.73		mJ

Electrical Characteristics of the IGBT (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
Qg	Total Gate Charge		-	123	-	nC
Q _{ge}	Gate to Emitter Charge	V _{CE} = 400 V, I _C = 75 A, V _{GE} = 15 V	-	22.6	-	nC
Q_{gc}	Gate to Collector Charge	VGE - 10 V	-	44.9	-	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Condition	ns	Min.	Тур.	Max	Unit
V _{FM}	Diode Forward Voltage	I _F = 75 A	T _C = 25°C	-	1.8	2.1	V
FM	Blode Folward Voltage	IF - 75 A	$T_{\rm C} = 175^{\rm o}{\rm C}$	-	1.7	-	
E _{rec}	Reverse Recovery Energy		T _C = 175°C	-	160	-	uJ
t _{rr}	Diode Reverse Recovery Time	I _F =75 A, dI _F /dt = 200 A/μs	$T_{\rm C} = 25^{\rm o}{\rm C}$	/ -	76	-	ns
भा	2.000 1.010.00 1.00010.9 1		$T_{\rm C} = 175^{\rm o}{\rm C}$	-	270	-	
Q _{rr}	Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\rm o}{\rm C}$	\ ' -	206	-	nC
% II	2.000 November 1.000 November 1		$T_{\rm C} = 175^{\rm o}{\rm C}$	1	2199	ı	:

Figure 1. Typical Output Characteristics

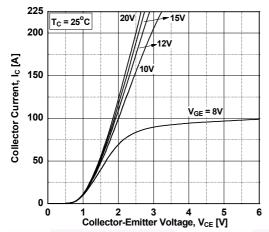


Figure 3. Typical Saturation Voltage Characteristics

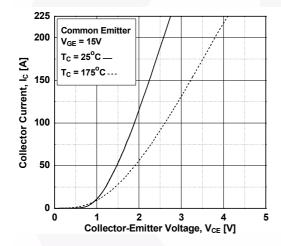


Figure 5. Saturation Voltage vs. V_{GE}

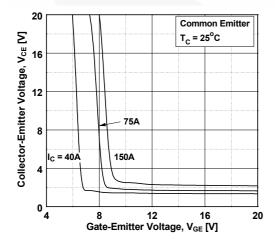


Figure 2. Typical Output Characteristics

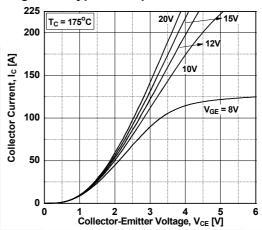


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

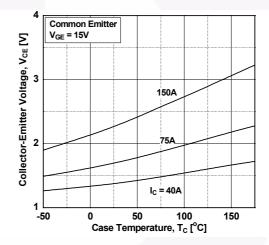


Figure 6. Saturation Voltage vs. V_{GE}

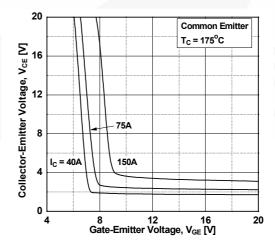


Figure 7. Capacitance Characteristics

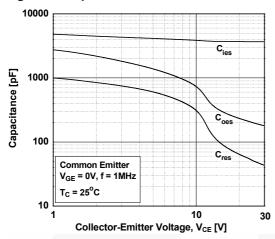


Figure 9. Turn-on Characteristics vs. Gate Resistance

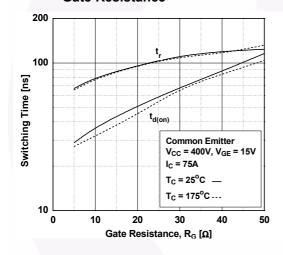


Figure 11. Switching Loss vs.

Gate Resistance

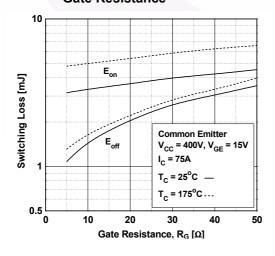


Figure 8. Gate charge Characteristics

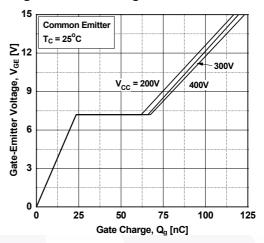


Figure 10. Turn-off Characteristics vs. Gate Resistance

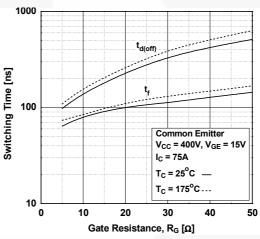


Figure 12. Turn-on Characteristics vs. Collector Current

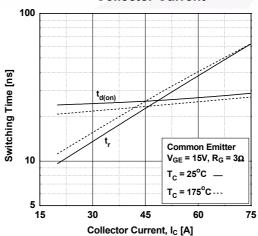
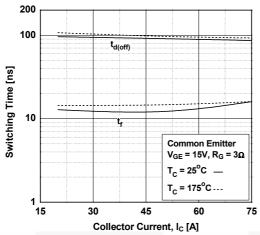


Figure 13. Turn-off Characteristics vs. Collector Current



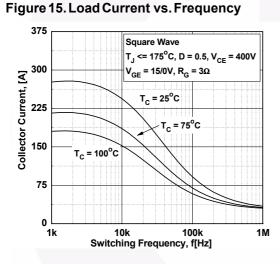


Figure 17. Forward Characteristics

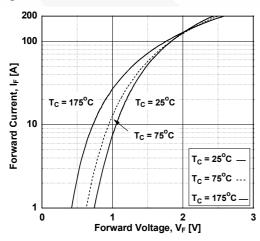


Figure 14. Switching Loss vs. Collector Current

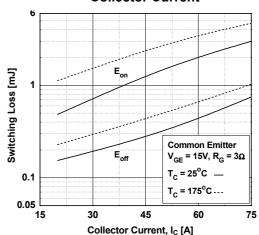


Figure 16. SOA Characteristics

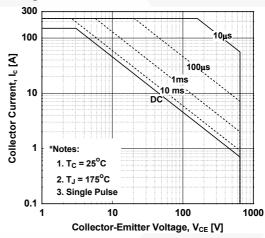


Figure 18. Reverse Recovery Current

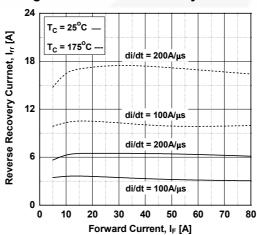


Figure 19. Reverse Recovery Time

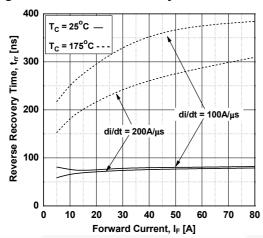


Figure 20. Stored Charge

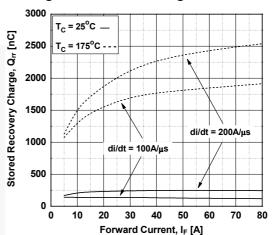


Figure 21.Transient Thermal Impedance of IGBT

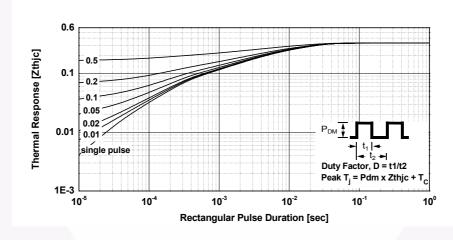
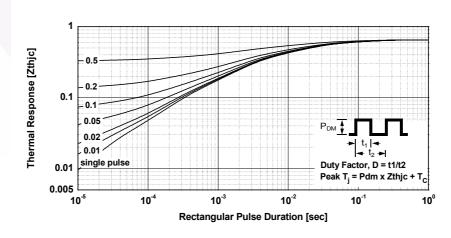
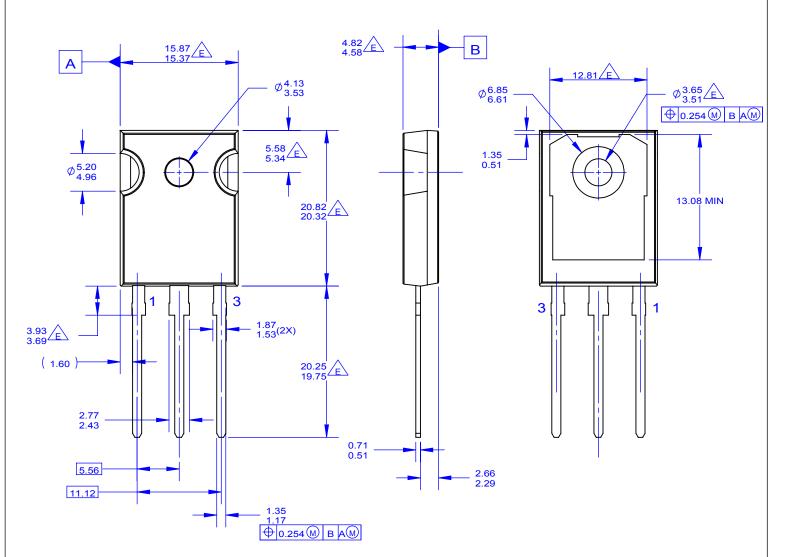


Figure 22. Transient Thermal Impedance of Diode





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